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Quartz crystal units of assessed quality – Part 1: Generic specification

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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Quartz crystal units of assessed quality – Part 1: Generic specification

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QUARTZ CRYSTAL UNITS OF ASSESSED QUALITY –

Part 1: Generic specification

FOREWORD

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This Consolidated version of IEC 60122-1 bears the edition number 3.1. It consists of the third edition (2002-08) [documents 49/551/FDIS and 49/558/RVD] and its amendment 1 (2017-12) [documents 49/1254/FDIS and 49/1259/RVD]. The technical content is identical to the base edition and its amendment.

In this Redline version, a vertical line in the margin shows where the technical content is modified by amendment 1. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.

International Standard IEC 60122-1 has been prepared by IEC technical committee 49: Piezoelectric and dielectric devices for frequency control and selection.

This third edition of IEC 60122-1 constitutes a technical revision.

International Standard IEC 60122-1 is the first part of a new edition of the IEC standard series for quartz crystal units of assessed quality.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

IEC 60122 consists of the following parts under the general title: Quartz crystal units of assessed quality:

- Part 1: Generic specification (IEC 60122-1);
- Part 2: Guide to the use of quartz crystal units for frequency control and selection (IEC 60122-2 at present);
- Part 3: Standard outlines and lead connections (IEC 60122-3);
- Part 4: Sectional specification – Capability Approval (IEC 61178-2 at present);
- Part 4-1: Blank detail specification – Capability Approval (IEC 61178-2-1 at present);
- Part 5: Sectional specification – Qualification Approval (IEC 61178-3 at present);
- Part 5-1: Blank detail specification – Qualification Approval (IEC 61178-3-1 at present).

The QC number which appears on the front cover of this publication is the specification number in the IEC Quality Assessment System for Electronic Components (IECQ).

The committee has decided that the contents of the base publication and its amendment will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
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QUARTZ CRYSTAL UNITS OF ASSESSED QUALITY –

Part 1: Generic specification

1 General

1.1 Scope

This part of IEC 60122 specifies the methods of test and general requirements for quartz crystal units of assessed quality using either capability approval or qualification approval procedures.

1.2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60027(all parts), *Letter symbols to be used in electrical technology*

IEC 60050(561):1991, *International Electrotechnical Vocabulary (IEV) – Chapter 561: Piezoelectric devices for frequency control and selection*

IEC 60068-1:1988, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-1:1990, *Environmental testing – Part 2: Tests – Tests A: Cold*

IEC 60068-2-2:1974, *Environmental testing – Part 2: Tests – Tests B: Dry heat*

IEC 60068-2-3:1969, *Environmental testing – Part 2: Tests – Test Ca: Damp heat, steady state*

IEC 60068-2-6:1995, *Environmental testing – Part 2: Tests – Test Fc: Vibration (sinusoidal)*

IEC 60068-2-7:1983, *Environmental testing – Part 2: Tests – Test Ga: Acceleration, steady state*

IEC 60068-2-13:1983, *Environmental testing – Part 2: Tests – Test M: Low air pressure*

IEC 60068-2-14:1984, *Environmental testing – Part 2: Tests – Test N: Change of temperature*

IEC 60068-2-17:1994, *Basic environmental testing procedures – Part 2: Tests – Test Q: Sealing*

IEC 60068-2-20:1979, *Environmental testing – Part 2: Tests – Test T: Soldering*

IEC 60068-2-21:1999, *Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices*

IEC 60068-2-27:1987, *Environmental testing – Part 2: Tests – Test Ea and guidance: Shock*

IEC 60068-2-29:1987, *Environmental testing – Part 2: Tests – Test Eb and guidance: Bump*

IEC 60068-2-30:1980, *Environmental testing – Part 2: Tests – Test Db and guidance: Damp heat, cyclic (12 + 12-hour cycle)*

IEC 60068-2-32:1975, *Environmental testing – Part 2: Tests – Test Ed: Free fall (Procedure 1)*

IEC 60068-2-45:1980, *Environmental testing – Part 2: Tests – Test XA and guidance: Immersion in cleaning solvents*

IEC 60122-3:2001, *Quartz crystal units of assessed quality – Part 3: Standard outlines and lead connections*

IEC 60444-1:1986, *Measurement of quartz crystal unit parameters by zero phase technique in a π -network – Part 1: Basic method for the measurement of resonance frequency and resonance resistance of quartz crystal units by zero phase techniques in a π -network*

IEC 60444-2:1980, *Measurement of quartz crystal unit parameters by zero phase technique in a π -network – Part 2: Phase offset method for the measurement of motional capacitance of quartz crystal units*

IEC 60444-4:1988, *Measurement of quartz crystal unit parameters by zero phase technique in a π -network – Part 4: Method for the measurement of the load resonance frequency f_L , load resonance resistance R_L and the calculation of other derived values of quartz crystal units, up to 30 MHz*

IEC 60444-5:1995, *Measurement of quartz crystal unit parameters – Part 5: Methods for the determination of equivalent electrical parameters using automatic network analyzer techniques and error corrections*

IEC 60444-6:1995, *Measurement of quartz crystal unit parameters – Part 6: Measurement of drive level dependence (DLD)*

IEC 60617 (all parts), *Graphical symbols for diagrams*

IEC 61178-2:1993, *Quartz crystal units – A specification in the IEC Quality Assessment System for Electronic Components (IECQ) – Part 2: Sectional specification – Capability approval*

IEC 61178-3:1993, *Quartz crystal units – A specification in the IEC Quality Assessment System for Electronic Components (IECQ) – Part 3: Sectional specification – Qualification approval*

IEC 61760-1:2006, *Surface mounting technology – Part 1: Standard method for the specification of surface mounting components (SMDs)*

IEC QC 001001:2000, *IEC Quality Assessment System for Electronic Components (IECQ) – Basic Rules*

IEC QC 001002-2:1998, *IEC Quality Assessment System for Electronic Components (IECQ) – Rules of Procedure – Part 2: Documentation*

IEC QC 001002-3:1998, *IEC Quality Assessment System for Electronic Components (IECQ) – Rules of Procedure – Part 3: Approval Procedures*

IEC QC 001005:2000, *Register of firms, products and services approved under the IECQ System, including ISO 9000*

ISO 1000:1992, *SI units and recommendations for the use of their multiples and of certain other units*

1.3 Order of precedence

Where any discrepancies occur for any reason, documents shall rank in the following order of precedence:

- the detail specification;
- the sectional specification;

- the generic specification;
- any other international documents (for example of the IEC) to which reference is made.

The same order of precedence shall apply to equivalent national documents.

FINAL VERSION

**Quartz crystal units of assessed quality –
Part 1: Generic specification**



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QUARTZ CRYSTAL UNITS OF ASSESSED QUALITY –

Part 1: Generic specification

FOREWORD

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This Consolidated version of IEC 60122-1 bears the edition number 3.1. It consists of the third edition (2002-08) [documents 49/551/FDIS and 49/558/RVD] and its amendment 1 (2017-12) [documents 49/1254/FDIS and 49/1259/RVD]. The technical content is identical to the base edition and its amendment.

This Final version does not show where the technical content is modified by amendment 1. A separate Redline version with all changes highlighted is available in this publication.

International Standard IEC 60122-1 has been prepared by IEC technical committee 49: Piezoelectric and dielectric devices for frequency control and selection.

This third edition of IEC 60122-1 constitutes a technical revision.

International Standard IEC 60122-1 is the first part of a new edition of the IEC standard series for quartz crystal units of assessed quality.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

IEC 60122 consists of the following parts under the general title: Quartz crystal units of assessed quality:

- Part 1: Generic specification (IEC 60122-1);
- Part 2: Guide to the use of quartz crystal units for frequency control and selection (IEC 60122-2 at present);
- Part 3: Standard outlines and lead connections (IEC 60122-3);
- Part 4: Sectional specification – Capability Approval (IEC 61178-2 at present);
- Part 4-1: Blank detail specification – Capability Approval (IEC 61178-2-1 at present);
- Part 5: Sectional specification – Qualification Approval (IEC 61178-3 at present);
- Part 5-1: Blank detail specification – Qualification Approval (IEC 61178-3-1 at present).

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A bilingual version of this publication may be issued at a later date.

QUARTZ CRYSTAL UNITS OF ASSESSED QUALITY –

Part 1: Generic specification

1 General

1.1 Scope

This part of IEC 60122 specifies the methods of test and general requirements for quartz crystal units of assessed quality using either capability approval or qualification approval procedures.

1.2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60027(all parts), *Letter symbols to be used in electrical technology*

IEC 60050(561):1991, *International Electrotechnical Vocabulary (IEV) – Chapter 561: Piezoelectric devices for frequency control and selection*

IEC 60068-1:1988, *Environmental testing – Part 1: General and guidance*

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IEC 60068-2-7:1983, *Environmental testing – Part 2: Tests – Test Ga: Acceleration, steady state*

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IEC 60068-2-20:1979, *Environmental testing – Part 2: Tests – Test T: Soldering*

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IEC QC 001002-3:1998, *IEC Quality Assessment System for Electronic Components (IECQ) – Rules of Procedure – Part 3: Approval Procedures*

IEC QC 001005:2000, *Register of firms, products and services approved under the IECQ System, including ISO 9000*

ISO 1000:1992, *SI units and recommendations for the use of their multiples and of certain other units*

1.3 Order of precedence

Where any discrepancies occur for any reason, documents shall rank in the following order of precedence:

- the detail specification;
- the sectional specification;

- the generic specification;
- any other international documents (for example of the IEC) to which reference is made.

The same order of precedence shall apply to equivalent national documents.